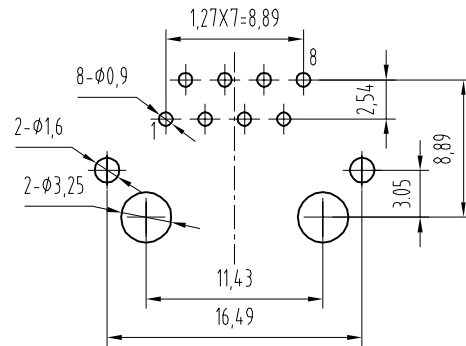
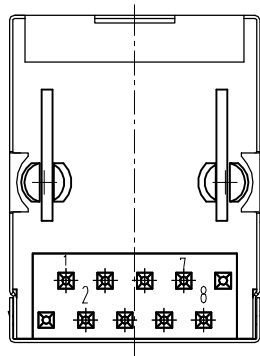
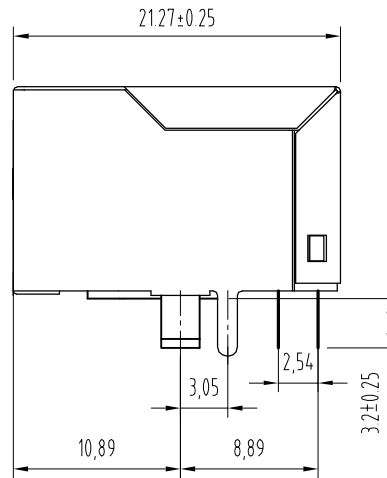
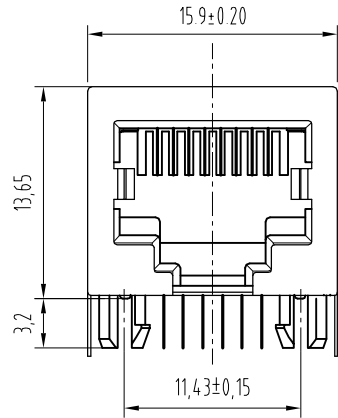


REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD



PC Board Layout
Component Side Shown

NOTES:

MATERIAL :

- 1.HOUSING MATERIAL
- 2.CONTACT MATERIAL
- 3.PLATING
- 4.SHIELD

- :GLASS FILLED POLYESTER UL94V-0.
- :PHOSPHOR BRONZE Ø0.45mm.
- :GOLD PLATING OVER NICKEL.
- :0.20mm THICKNESS COPPER ALLOY WITH NICKEL PLATED.

ELECTRICAL:

- 1.VOLTAGE RATING
- 2.CURRENT RATING
- 3.CONTACT RESISTANCE
- 4.INSULATION RESISTANCE
- 5.DIELECTRIC WITHSTANDING RESISTANCE

- :125 VAC RMS.
- :15 AMP.
- :30 MILLIOHMS MAX.
- :500 MEGOHMS MIN @ 500V DC .
- :1000V AC RMS 50Hz. 1MIN.

MECHANICAL:

- 1.DURRABILITY
- 2.PCB RETENTION PRE-SOLDER

- :750 CYCLES MIN.
- :1 LB MIN.

ENVIRONMENTAL:

1. STORAGE
2. OPERATION

- : -40°C~+85°C
- : 0°C TO 70°C.

DEFINITIONS TOLERANCES EXCEPT AS NOTED	MM BIMCHI	DFTO: SHB	DATE: 2007.05.03	<h1>Coorle Technology</h1>	
	MM	CHKD: LANBO	DATE: 2007.05.03		
	MM	MFO:	DATE:		
	MM	APPVL:	DATE:		
MM .1 ± 0.15 .18 ± 0.075 .25 ± 0.15	MM	MATERIAL :		TITLE	
ANGLES ± 0.5	MM	QTY :		59A 10P8C JACK W/ SHIELD	
THIRD ANGLE PROJECTION	MM	FINISH :		DRAWING NO. TESPA10ML	SIZE
	MM	SCALE :		/PART NO.	A3
	MM			DO NOT SCALE DRAWING	REV
	MM			SHEET X	0
	MM			OF Y	